L Number	Hits	Search Text	DB	Time stamp
1	376933	retract$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:03
2	2617875	wafer or substrate or pedestal or receiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:03
3	6986	retract$5 with (wafer or substrate or pedestal or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:03
4	46343	(coating or sputtering or depositing) near2 apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:03
5	11	(retract$5 with (wafer or substrate or pedestal or receiver)) same ((coating or sputtering or depositing) near2 apparatus)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:04
6	263	(retract$5 with (wafer or substrate or pedestal or receiver)) and ((coating or sputtering or depositing) near2 apparatus)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:04
7	252	((retract$5 with (wafer or substrate or pedestal or receiver)) and ((coating or sputtering or depositing) near2 apparatus)) not ((retract$5 with (wafer or substrate or pedestal or receiver)) same ((coating or sputtering or depositing) near2 apparatus))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:07

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